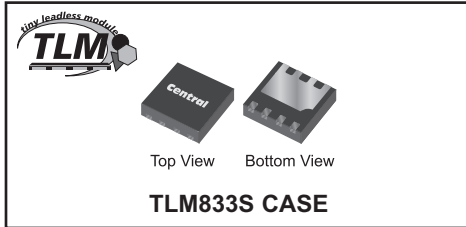


CTLT953-M833S**SURFACE MOUNT
HIGH CURRENT
PNP SILICON TRANSISTOR**
www.centrasemi.com
DESCRIPTION:

The CENTRAL SEMICONDUCTOR CTLT953-M833S is a high performance 5.0A high current PNP transistor designed for applications where small size and operational efficiency are prime requirements. With a maximum power dissipation of 4.5W, and a very small package footprint, this device is 80% smaller than a comparable SOT-223 device. This leadless package design has a power density at least twice that of equivalent package devices.

MARKING CODE: CHA4S**APPLICATIONS:**

- Motor control
- Load switches
- Display drives
- Relay drives

FEATURES:

- High Voltage (140V)
- High Current (5.0A)
- Low $V_{CE(SAT)}$ (420mV MAX @ 4.0A)
- High Thermal Efficiency
- 3 x 3mm TLM™ case

MAXIMUM RATINGS: ($T_A=25^\circ\text{C}$)

Collector-Base Voltage
Collector-Emitter Voltage
Emitter-Base Voltage
Continuous Collector Current
Power Dissipation (Note 1)
Power Dissipation (Note 2)
Power Dissipation (Note 3)
Operating and Storage Junction Temperature
Thermal Resistance (Note 1)
Thermal Resistance (Note 2)
Thermal Resistance (Note 3)

SYMBOL		UNITS
V_{CBO}	140	V
V_{CEO}	100	V
V_{EBO}	6.0	V
I_C	5.0	A
P_D	4.5	W
P_D	4.0	W
P_D	2.5	W
T_J, T_{stg}	-65 to +150	$^\circ\text{C}$
θ_{JA}	27.78	$^\circ\text{C/W}$
θ_{JA}	31.25	$^\circ\text{C/W}$
θ_{JA}	50.00	$^\circ\text{C/W}$

ELECTRICAL CHARACTERISTICS: ($T_A=25^\circ\text{C}$ unless otherwise noted)

SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS
I_{CBO}	$V_{CB}=100\text{V}$			50	nA
I_{CBO}	$V_{CB}=100\text{V}, T_A=100^\circ\text{C}$			1.0	μA
I_{CER}	$V_{CE}=100\text{V}, R_{BE}\leq 1.0\text{k}\Omega$			50	nA
I_{EBO}	$V_{EB}=6.0\text{V}$			10	nA
BV_{CBO}	$I_C=100\mu\text{A}$	140	170		V
BV_{CER}	$I_C=10\text{mA}, R_{BE}\leq 1.0\text{k}\Omega$	140	150		V
BV_{CEO}	$I_C=10\text{mA}$	100	120		V
BV_{EBO}	$I_E=100\mu\text{A}$	6.0	9.0		V
$V_{CE(SAT)}$	$I_C=100\text{mA}, I_B=10\text{mA}$		20	50	mV
$V_{CE(SAT)}$	$I_C=1.0\text{A}, I_B=100\text{mA}$		90	120	mV
$V_{CE(SAT)}$	$I_C=2.0\text{A}, I_B=200\text{mA}$		170	220	mV
$V_{CE(SAT)}$	$I_C=4.0\text{A}, I_B=400\text{mA}$		320	420	mV
$V_{BE(SAT)}$	$I_C=4.0\text{A}, I_B=400\text{mA}$		1.0	1.2	V

Notes: (1) Ceramic or aluminum core PC Board with copper mounting pad area of 75 mm²
 (2) FR-4 Epoxy PC Board with copper mounting pad area of 75 mm²
 (3) FR-4 Epoxy PC Board with copper mounting pad area of 25 mm²

R0 (8-August 2012)

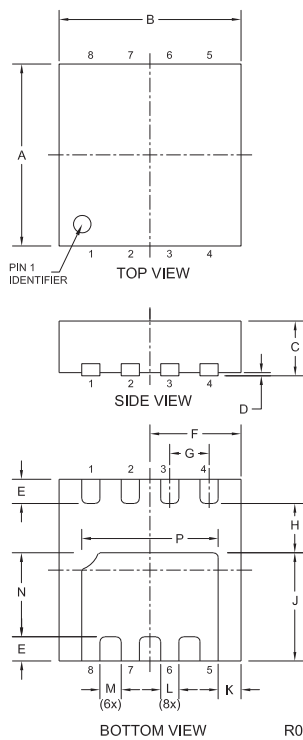
CTLT953-M833S
SURFACE MOUNT
HIGH CURRENT
PNP SILICON TRANSISTOR



ELECTRICAL CHARACTERISTICS - Continued: ($T_A=25^\circ\text{C}$ unless otherwise noted)

SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS
h_{FE}	$V_{CE}=1.0\text{V}, I_C=10\text{mA}$	100			
h_{FE}	$V_{CE}=1.0\text{V}, I_C=1.0\text{A}$	100	200	300	
h_{FE}	$V_{CE}=1.0\text{V}, I_C=3.0\text{A}$	50	70		
h_{FE}	$V_{CE}=1.0\text{V}, I_C=4.0\text{A}$	30	45		
h_{FE}	$V_{CE}=1.0\text{V}, I_C=10\text{A}$		15		
f_T	$V_{CE}=10\text{V}, I_C=100\text{mA}, f=50\text{MHz}$		150		MHz
C_{ob}	$V_{CB}=10\text{V}, I_E=0, f=1.0\text{MHz}$		45		pF

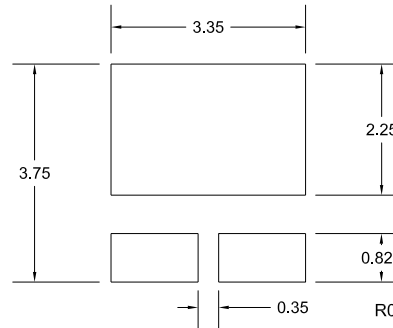
TLM833S CASE - MECHANICAL OUTLINE



SYMBOL	DIMENSIONS			
	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.112	0.124	2.85	3.15
B	0.112	0.124	2.85	3.15
C	0.031	0.039	0.80	1.00
D	0.000	0.002	0.00	0.05
E	0.012	0.020	0.30	0.50
F	0.056	0.062	1.43	1.57
G	0.026		0.65	
H	0.030	0.033	0.75	0.85
J	0.065	0.073	1.65	1.85
K	0.012	0.016	0.30	0.40
L	0.010	0.014	0.25	0.35
M	0.012	0.016	0.30	0.40
N	0.047	0.057	1.20	1.45
P	0.081	0.091	2.07	2.32

TLM833S (REV:R0)

REQUIRED MOUNTING PADS
(Dimensions in mm)



Failure to use this mounting pad layout may result in damage to device.

R0 (8-August 2012)

LEAD CODE:

- | | |
|------------|--------------|
| 1) Emitter | 5) Collector |
| 2) Emitter | 6) Collector |
| 3) Base | 7) Collector |
| 4) N.C. | 8) Collector |

MARKING CODE: CHA4S

OUTSTANDING SUPPORT AND SUPERIOR SERVICES



PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- Inventory bonding
- Consolidated shipping options
- Custom bar coding for shipments
- Custom product packing

DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free quick ship samples (2nd day air)
- Online technical data and parametric search
- SPICE models
- Custom electrical curves
- Environmental regulation compliance
- Customer specific screening
- Up-screening capabilities
- Special wafer diffusions
- PbSn plating options
- Package details
- Application notes
- Application and design sample kits
- Custom product and package development

CONTACT US

Corporate Headquarters & Customer Support Team

Central Semiconductor Corp.
145 Adams Avenue
Hauppauge, NY 11788 USA
Main Tel: (631) 435-1110
Main Fax: (631) 435-1824
Support Team Fax: (631) 435-3388
www.centalsemi.com

Worldwide Field Representatives:
www.centalsemi.com/wwreps

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